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TRANSMITTAL FORM (to be used for all correspondence after initial filing)	Application Number	09/707,844	
	Filing Date	November 8, 2000	
	First Named Inventor	Hidetoshi ISHIDA et al.	
	Group Art Unit	2814	
	Examiner Name	Dana FARAHANI	
Total Number of Pages in This Submission	1	Attorney Docket Number	740819-448

ENCLOSURES (check all that apply)		
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#7A AND

M. Brunson

PATENT 740819-448

9/5/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Hidetoshi ISHIDA et al.

Serial No. 09/707,844

Filed: November 8, 2000

For: SEMICONDUCTOR DEVICE

) Group Art Unit: 2814

) Examiner: Dana FARAHAANI

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Examiner's non-final Office Action mailed May 29, 2002, please consider the following amendments and remarks in connection with the above-identified application.

IN THE CLAIMS:

Please amend claims 1 and 6 as follows:

Sub B1
1. (Amended) A semiconductor device comprising:
a semiconductor substrate;
at least two semiconductor components provided on the principal surface of the substrate; and
multiple through holes, which pass from the principal surface through the backside of the substrate and are provided in a region of the substrate between the at least two components so as to substantially eliminate the electrical interference between the two semiconductor components.

Sub B2
6. (Amended) A semiconductor device comprising: